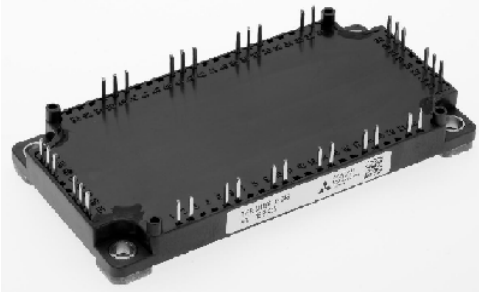


<IGBT Modules>

CM100TX-24S

**HIGH POWER SWITCHING USE
INSULATED TYPE**



sixpack (3φ Inverter)

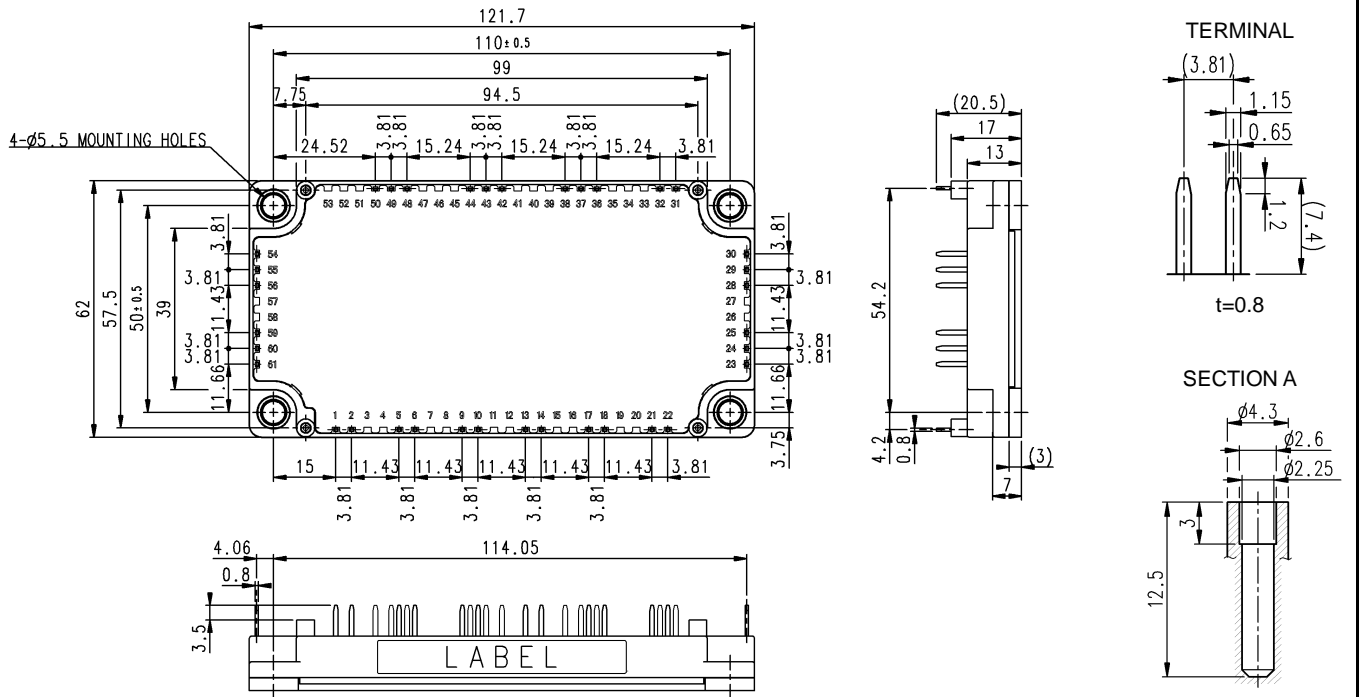
Collector current I_C **1 0 0 A**
 Collector-emitter voltage V_{CES} **1 2 0 0 V**
 Maximum junction temperature T_{jmax} **1 7 5 °C**

- Flat base Type
- Copper base plate (non-plating)
- Tin plating pin terminals
- RoHS Directive compliant
- Recognized under UL1557, File E323585

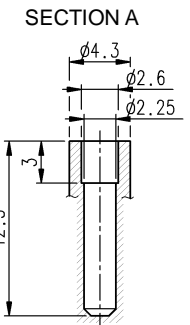
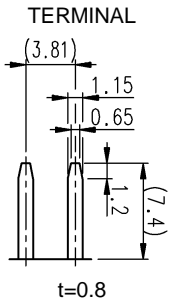
APPLICATION

AC Motor Control, Motion/Servo Control, Power supply, etc.

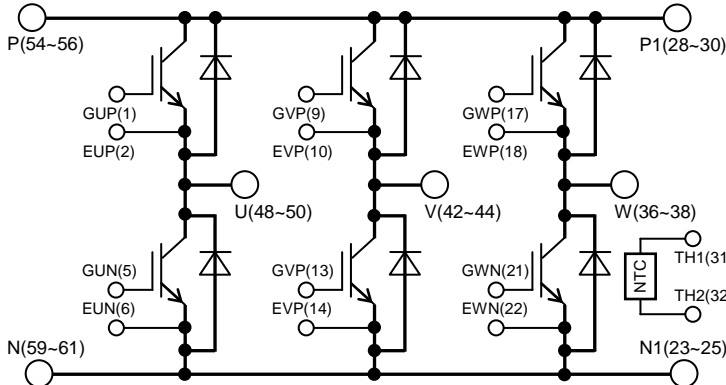
OUTLINE DRAWING & INTERNAL CONNECTION



Dimension in mm



INTERNAL CONNECTION



Caution: Each (three) pin terminal of P/N/P1/N1/U/V/W is connected in the module, but should use all each three pins for the external wiring.

Tolerance otherwise specified

Division of Dimension	Tolerance
0.5 to 3	±0.2
over 3 to 6	±0.3
over 6 to 30	±0.5
over 30 to 120	±0.8
over 120 to 400	±1.2

The tolerance of size between terminals is assumed to be ±0.4.

CM100TX-24S

HIGH POWER SWITCHING USE
INSULATED TYPEMAXIMUM RATINGS ($T_j=25\text{ }^\circ\text{C}$, unless otherwise specified)

INVERTER PART IGBT/DIODE

Symbol	Item	Conditions	Rating	Unit
V_{CES}	Collector-emitter voltage	G-E short-circuited	1200	V
V_{GES}	Gate-emitter voltage	C-E short-circuited	± 20	V
I_C	Collector current	DC, $T_C=119\text{ }^\circ\text{C}$ (Note2, 4)	100	A
I_{CRM}		Pulse, Repetitive (Note3)	200	
P_{tot}	Total power dissipation	$T_C=25\text{ }^\circ\text{C}$ (Note2, 4)	750	W
I_E (Note1)	Emitter current	DC (Note2)	100	A
I_{ERM} (Note1)		Pulse, Repetitive (Note3)	200	

MODULE

Symbol	Item	Conditions	Rating	Unit
V_{isol}	Isolation voltage	Terminals to base plate, RMS, $f=60\text{ Hz}$, AC 1 min	2500	V
T_{jmax}	Maximum junction temperature	Instantaneous event (overload)	175	$^\circ\text{C}$
T_{Cmax}	Maximum case temperature	(Note4)	125	$^\circ\text{C}$
T_{jop}	Operating junction temperature	Continuous operation (under switching)	-40 ~ +150	$^\circ\text{C}$
T_{stg}	Storage temperature	-	-40 ~ +125	

ELECTRICAL CHARACTERISTICS ($T_j=25\text{ }^\circ\text{C}$, unless otherwise specified)

INVERTER PART IGBT/DIODE

Symbol	Item	Conditions	Limits			Unit	
			Min.	Typ.	Max.		
I_{CES}	Collector-emitter cut-off current	$V_{CE}=V_{CES}$, G-E short-circuited	-	-	1.0	mA	
I_{GES}	Gate-emitter leakage current	$V_{GE}=V_{GES}$, C-E short-circuited	-	-	0.5	μA	
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C=10\text{ mA}$, $V_{CE}=10\text{ V}$	5.4	6.0	6.6	V	
V_{CESat} (Terminal)	Collector-emitter saturation voltage	$I_C=100\text{ A}$, $V_{GE}=15\text{ V}$, Refer to the figure of test circuit. (Note6)	$T_j=25\text{ }^\circ\text{C}$	-	1.80	2.25	V
V_{CESat} (Chip)			$T_j=125\text{ }^\circ\text{C}$	-	2.00	-	
			$T_j=150\text{ }^\circ\text{C}$	-	2.05	-	
		V_{CESat} (Chip)	$I_C=100\text{ A}$, $V_{GE}=15\text{ V}$, (Note6)	$T_j=25\text{ }^\circ\text{C}$	-	1.70	2.15
$T_j=125\text{ }^\circ\text{C}$				-	1.90	-	
$T_j=150\text{ }^\circ\text{C}$				-	1.95	-	
C_{ies}	Input capacitance	$V_{CE}=10\text{ V}$, G-E short-circuited	-	-	10	nF	
C_{oes}	Output capacitance		-	-	2.0		
C_{res}	Reverse transfer capacitance		-	-	0.17		
Q_G	Gate charge	$V_{CC}=600\text{ V}$, $I_C=100\text{ A}$, $V_{GE}=15\text{ V}$	-	233	-	nC	
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600\text{ V}$, $I_C=100\text{ A}$, $V_{GE}=\pm 15\text{ V}$, $R_G=6.2\text{ }\Omega$, Inductive load	-	-	300	ns	
t_r	Rise time		-	-	200		
$t_{d(off)}$	Turn-off delay time		-	-	600		
t_f	Fall time		-	-	300		
V_{EC} (Note1) (Terminal)	Emitter-collector voltage	$I_E=100\text{ A}$, G-E short-circuited, Refer to the figure of test circuit. (Note6)	$T_j=25\text{ }^\circ\text{C}$	-	1.80	2.25	V
V_{EC} (Note1) (Chip)			$T_j=125\text{ }^\circ\text{C}$	-	1.80	-	
			$T_j=150\text{ }^\circ\text{C}$	-	1.80	-	
		V_{EC} (Note1) (Chip)	$I_E=100\text{ A}$, G-E short-circuited, (Note6)	$T_j=25\text{ }^\circ\text{C}$	-	1.70	2.15
$T_j=125\text{ }^\circ\text{C}$				-	1.70	-	
$T_j=150\text{ }^\circ\text{C}$				-	1.70	-	
t_{rr} (Note1)	Reverse recovery time	$V_{CC}=600\text{ V}$, $I_E=100\text{ A}$, $V_{GE}=\pm 15\text{ V}$, $R_G=6.2\text{ }\Omega$, Inductive load	-	-	300	ns	
Q_{rr} (Note1)	Reverse recovery charge	$R_G=6.2\text{ }\Omega$, Inductive load	-	5.3	-	μC	
E_{on}	Turn-on switching energy per pulse	$V_{CC}=600\text{ V}$, $I_C=I_E=100\text{ A}$,	-	8.6	-	mJ	
E_{off}	Turn-off switching energy per pulse	$V_{GE}=\pm 15\text{ V}$, $R_G=6.2\text{ }\Omega$, $T_j=150\text{ }^\circ\text{C}$,	-	10.7	-		
E_{rr} (Note1)	Reverse recovery energy per pulse	Inductive load	-	10.2	-	mJ	
R_{CC+EE}	Internal lead resistance	Main terminals-chip, per switch, $T_C=25\text{ }^\circ\text{C}$ (Note4)	-	-	3.5	m Ω	
r_g	Internal gate resistance	Per switch	-	0	-	Ω	

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HIGH POWER SWITCHING USE
INSULATED TYPE

ELECTRICAL CHARACTERISTICS (cont.; T_j=25 °C, unless otherwise specified) NTC THERMISTOR PART

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R ₂₅	Zero-power resistance	T _C =25 °C (Note4)	4.85	5.00	5.15	kΩ
ΔR/R	Deviation of resistance	R ₁₀₀ =493 Ω, T _C =100 °C (Note4)	-7.3	-	+7.8	%
B _(25/50)	B-constant	Approximate by equation (Note6)	-	3375	-	K
P ₂₅	Power dissipation	T _C =25 °C (Note4)	-	-	10	mW

THERMAL RESISTANCE CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R _{th(j-c)Q}	Thermal resistance	Junction to case, per Inverter IGBT (Note4)	-	-	0.20	K/W
R _{th(j-c)D}		Junction to case, per Inverter DIODE (Note4)	-	-	0.29	
R _{th(c-s)}	Contact thermal resistance	Case to heat sink, per 1 module, Thermal grease applied (Note4, 7)	-	15	-	K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
M _s	Mounting torque	Mounting to heat sink M 5 screw	2.5	3.0	3.5	N·m
d _s	Creepage distance	Terminal to terminal	10.28	-	-	mm
		Terminal to base plate	12.41	-	-	
d _a	Clearance	Terminal to terminal	9.88	-	-	mm
		Terminal to base plate	12.41	-	-	
m	mass	-	-	300	-	g
e _c	Flatness of base plate	On the centerline X, Y (Note8)	±0	-	+100	μm

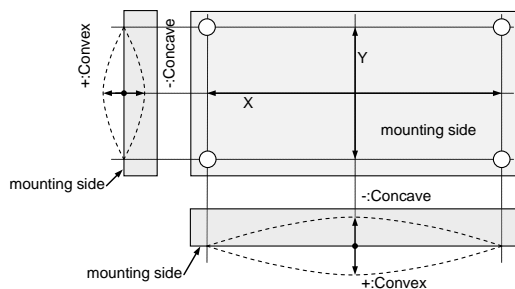
Note1. Represent ratings and characteristics of the anti-parallel, emitter-collector free wheeling diode (DIODE).

- Junction temperature (T_j) should not increase beyond T_{jm ax} rating.
- Pulse width and repetition rate should be such that the device junction temperature (T_j) dose not exceed T_{jm ax} rating.
- Case temperature (T_C) and heat sink temperature (T_s) are defined on the each surface (mounting side) of base plate and heat sink just under the chips. Refer to the figure of chip location.
- Pulse width and repetition rate should be such as to cause negligible temperature rise.
- B_(25/50) = $\ln\left(\frac{R_{25}}{R_{50}}\right) / \left(\frac{1}{T_{25}} - \frac{1}{T_{50}}\right)$,

R₂₅: resistance at absolute temperature T₂₅ [K]; T₂₅=25 [°C]+273.15=298.15 [K]

R₅₀: resistance at absolute temperature T₅₀ [K]; T₅₀=50 [°C]+273.15=323.15 [K]

- Typical value is measured by using thermally conductive grease of λ=0.9 W/(m·K).
- The base plate (mounting side) flatness measurement points (X, Y) are as follows of the following figure.



- Use the following screws when mounting the printed circuit board (PCB) on the stand offs.
"φ2.6×10 or φ2.6×12 self tapping screw"
The length of the screw depends on the thickness (t1.6~t2.0) of the PCB.

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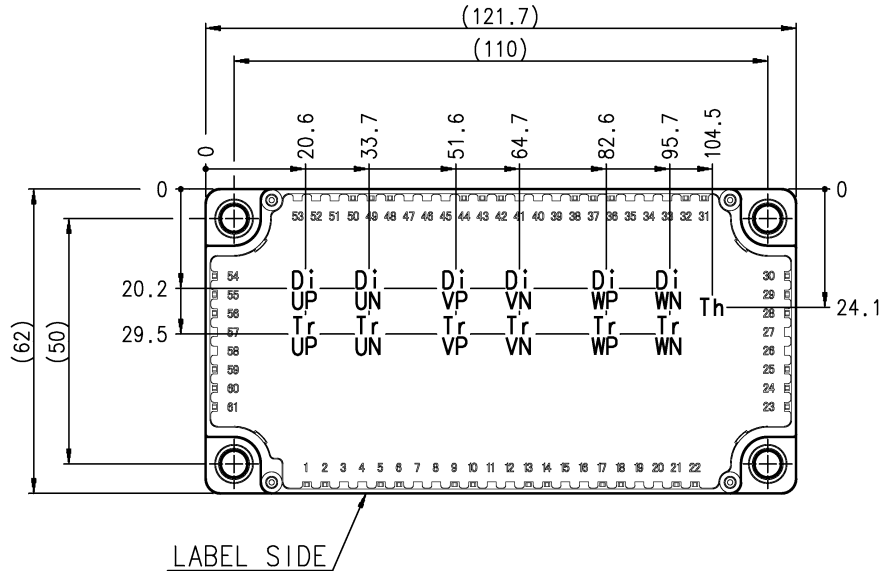
HIGH POWER SWITCHING USE
INSULATED TYPE

RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
V_{CC}	(DC) Supply voltage	Applied across P-N/P1-N1 terminals	-	600	850	V
V_{GEon}	Gate (-emitter drive) voltage	Applied across G*P-E*P/G*N-E*N (*=U, V, W) terminals	13.5	15.0	16.5	V
R_G	External gate resistance	Per switch	6.2	-	62	Ω

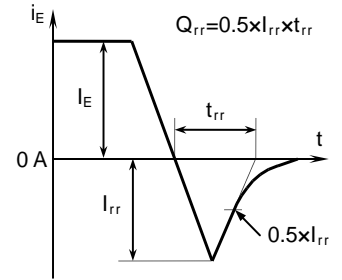
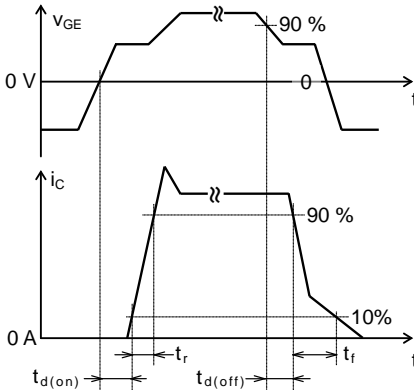
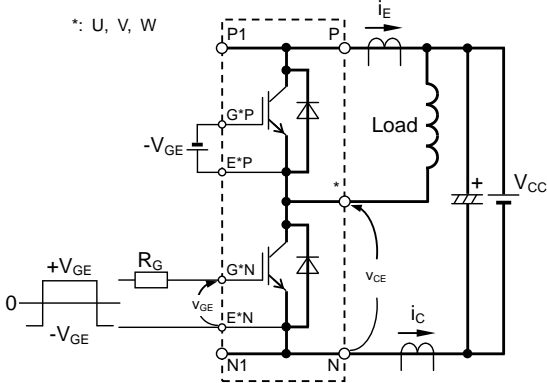
CHIP LOCATION (Top view)

Dimension in mm, tolerance: ± 1 mm



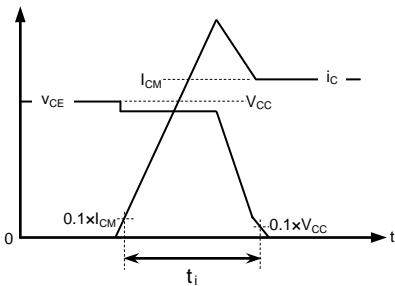
Tr*P/Tr*N/Tr*V: IGBT, Di*P/Di*N: DIODE (*=U/V/W), Th: NTC thermistor

TEST CIRCUIT AND WAVEFORMS

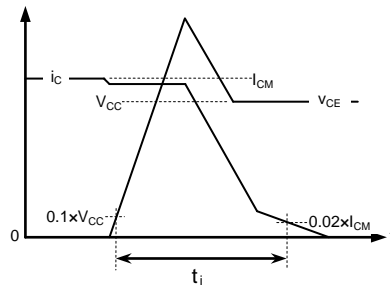


Switching characteristics test circuit and waveforms

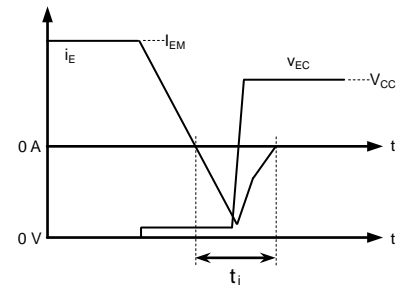
t_{rr} , Q_{rr} test waveform



IGBT Turn-on switching energy



IGBT Turn-off switching energy



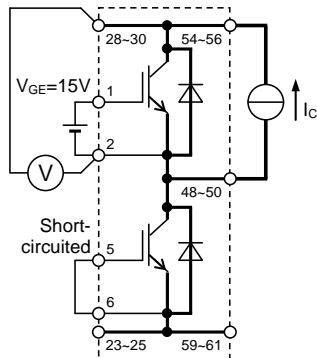
DIODE Reverse recovery energy

Turn-on / Turn-off switching energy and Reverse recovery energy test waveforms (Integral time instruction drawing)

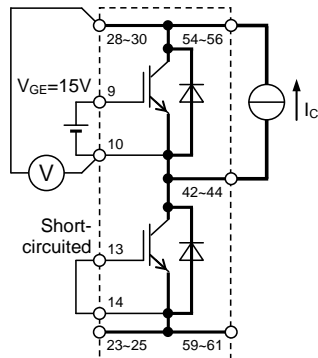
CM100TX-24S

HIGH POWER SWITCHING USE
INSULATED TYPE

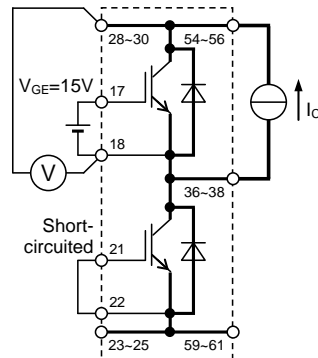
TEST CIRCUIT



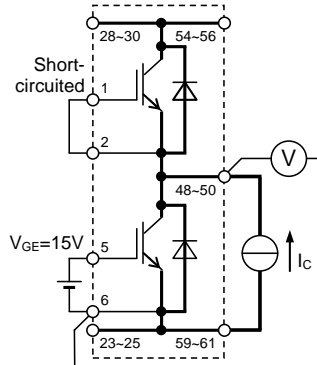
Gate-emitter GVP-EVP, GVN-EVP,
short-circuited GWP-EWN, GWN-EWN
UP / UN IGBT



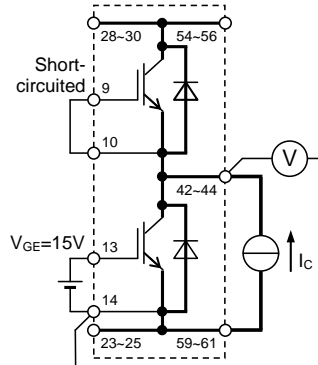
Gate-emitter GUP-EUP, GUN-EUN,
short-circuited GWP-EWP, GWN-EWN
VP / VN IGBT



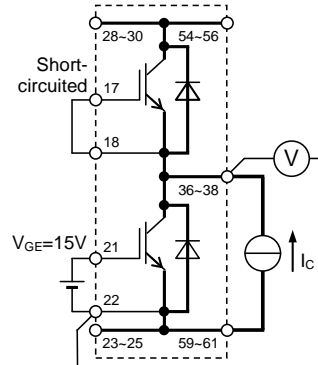
Gate-emitter GUP-EUP, GUN-EUN,
short-circuited GVP-EVP, GVN-EVN
WP / WN IGBT



Gate-emitter GVP-EVP, GVN-EVP,
short-circuited GWP-EWN, GWN-EWN
UP / UN DIODE

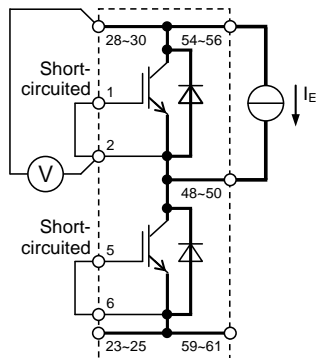


Gate-emitter GUP-EUP, GUN-EUN,
short-circuited GWP-EWP, GWN-EWN
VP / VN DIODE

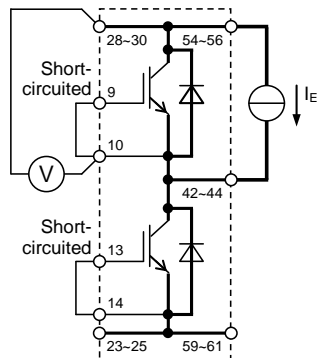


Gate-emitter GUP-EUP, GUN-EUN,
short-circuited GVP-EVP, GVN-EVN
WP / WN DIODE

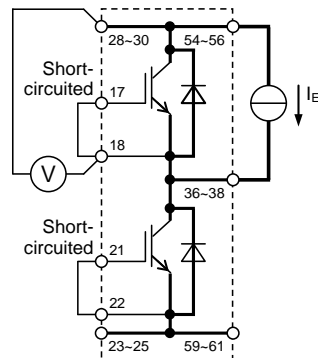
V_{CEsat} test circuit



Gate-emitter GVP-EVP, GVN-EVP,
short-circuited GWP-EWN, GWN-EWN
UP / UN DIODE



Gate-emitter GUP-EUP, GUN-EUN,
short-circuited GWP-EWP, GWN-EWN
VP / VN DIODE



Gate-emitter GUP-EUP, GUN-EUN,
short-circuited GVP-EVP, GVN-EVN
WP / WN DIODE

V_{EC} / V_F test circuit

CM100TX-24S

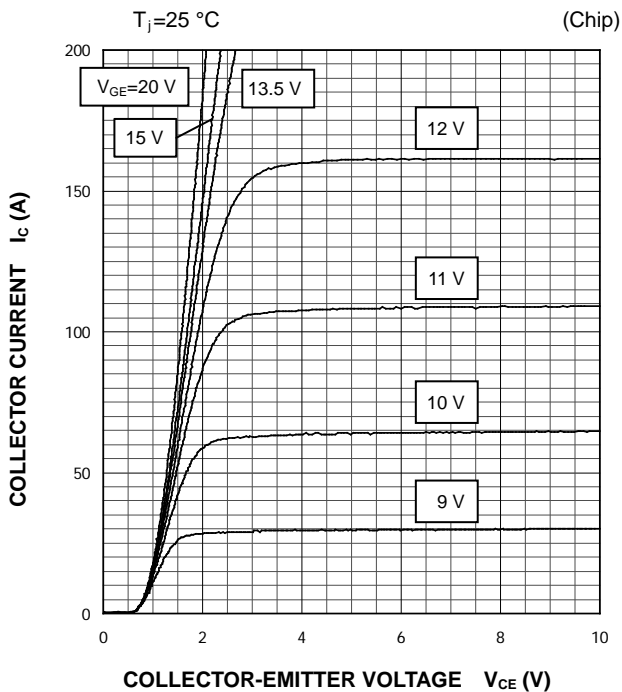
HIGH POWER SWITCHING USE
INSULATED TYPE

PERFORMANCE CURVES

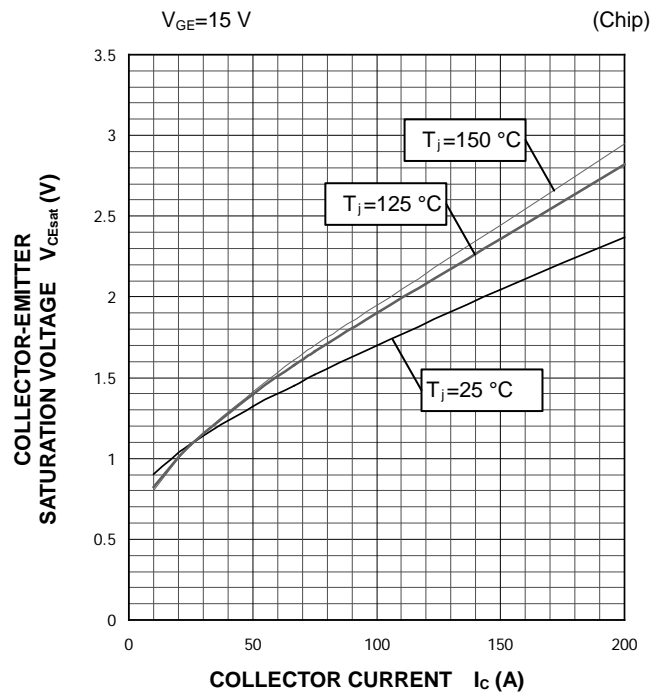
INVERTER PART

OUTPUT CHARACTERISTICS

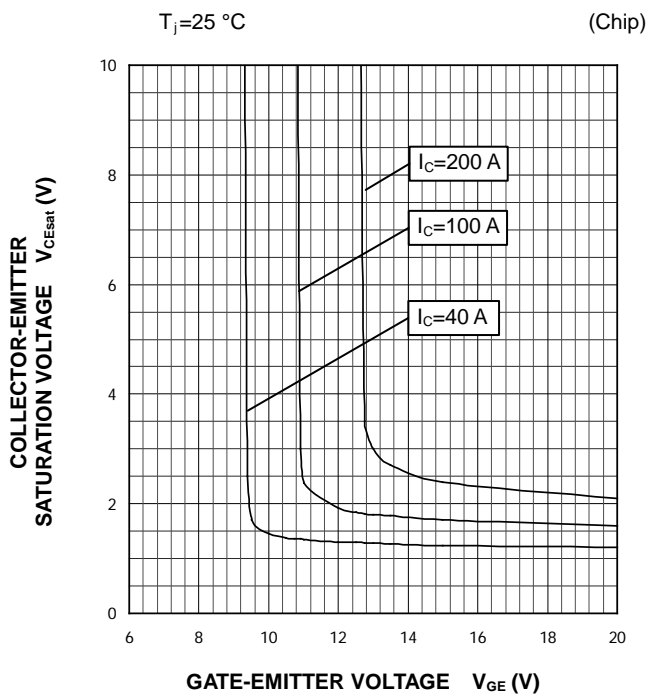
(TYPICAL)



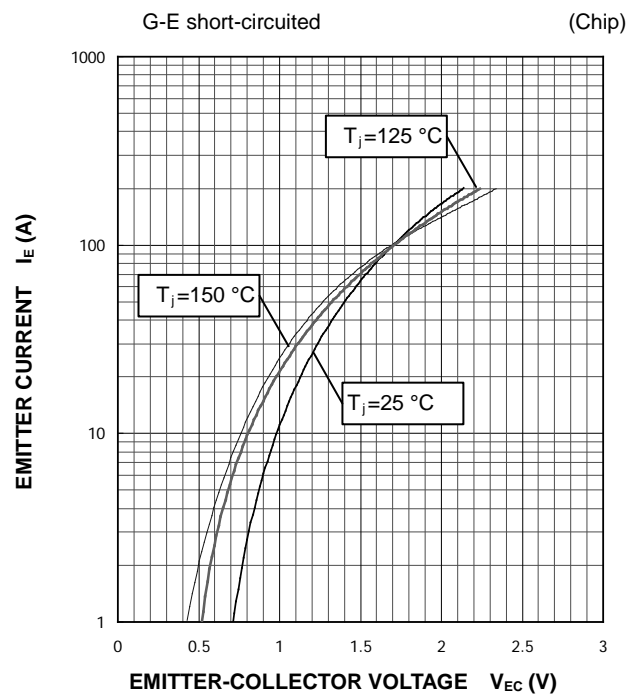
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)



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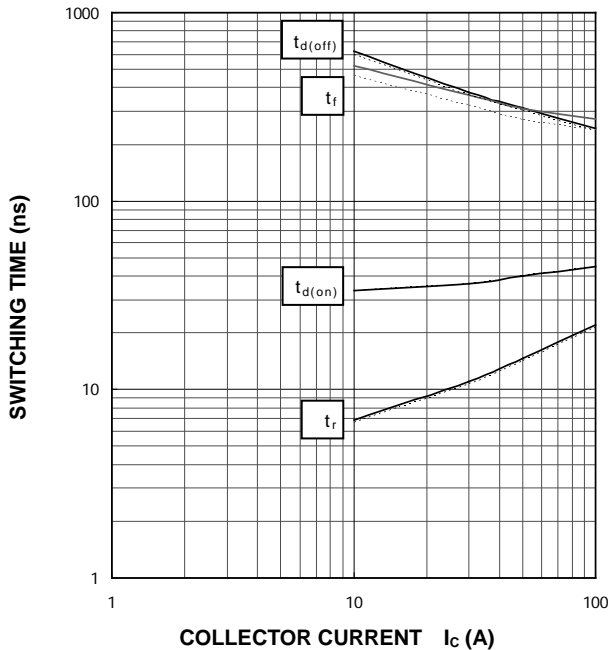
HIGH POWER SWITCHING USE
INSULATED TYPE

PERFORMANCE CURVES

INVERTER PART

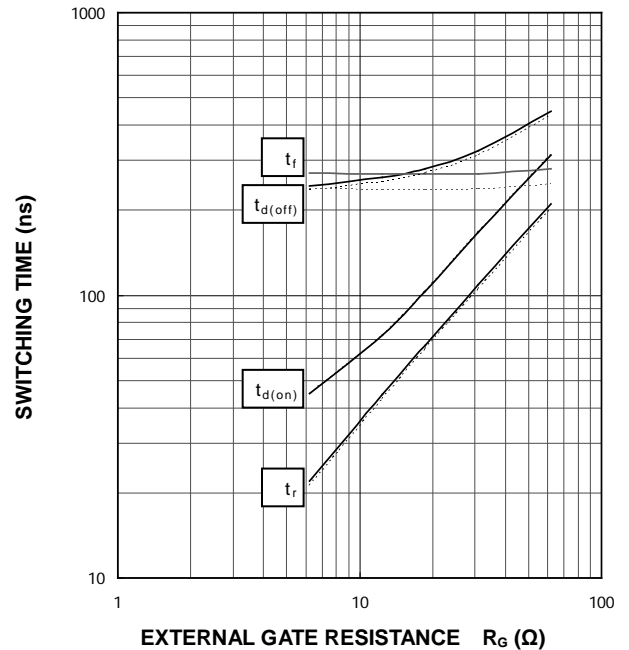
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{CC}=600\text{ V}$, $V_{GE}=\pm 15\text{ V}$, $R_G=6.2\ \Omega$, INDUCTIVE LOAD
——: $T_j=150\text{ }^\circ\text{C}$, - - - - -: $T_j=125\text{ }^\circ\text{C}$



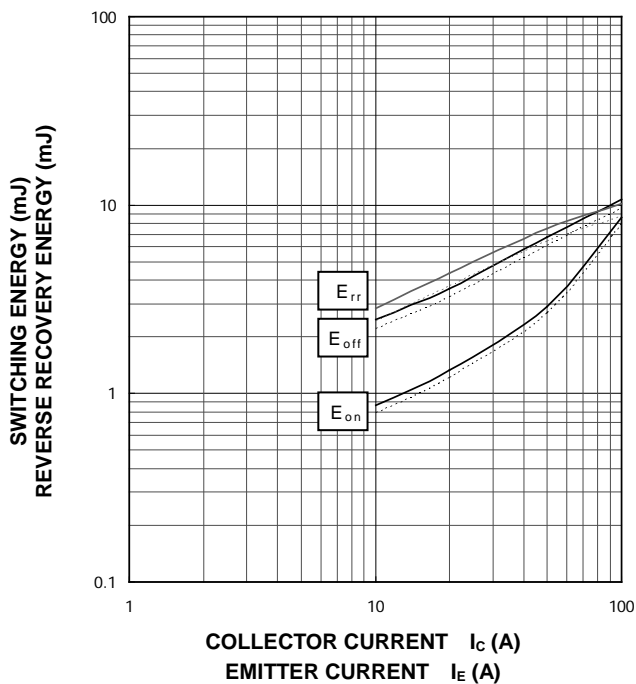
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{CC}=600\text{ V}$, $V_{GE}=\pm 15\text{ V}$, $I_C=100\text{ A}$, INDUCTIVE LOAD
——: $T_j=150\text{ }^\circ\text{C}$, - - - - -: $T_j=125\text{ }^\circ\text{C}$



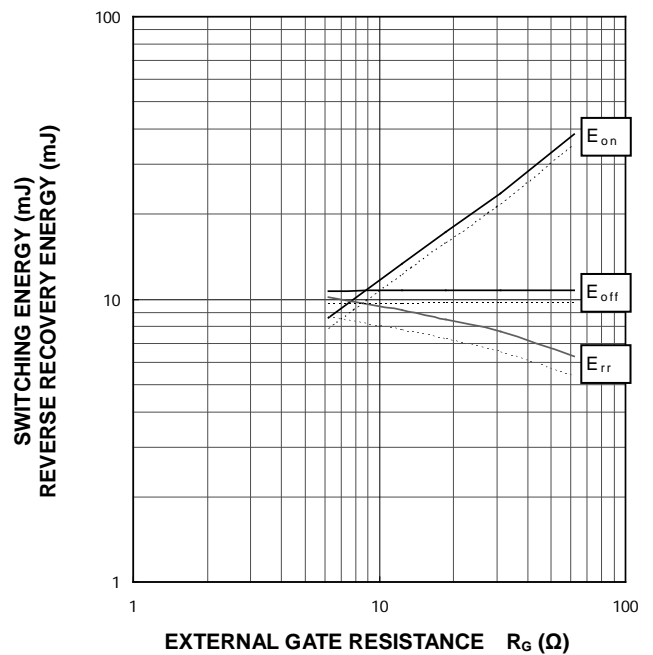
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{CC}=600\text{ V}$, $V_{GE}=\pm 15\text{ V}$, $R_G=6.2\ \Omega$,
INDUCTIVE LOAD, PER PULSE
——: $T_j=150\text{ }^\circ\text{C}$, - - - - -: $T_j=125\text{ }^\circ\text{C}$



HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

$V_{CC}=600\text{ V}$, $V_{GE}=\pm 15\text{ V}$, $I_C/I_E=100\text{ A}$,
INDUCTIVE LOAD, PER PULSE
——: $T_j=150\text{ }^\circ\text{C}$, - - - - -: $T_j=125\text{ }^\circ\text{C}$



CM100TX-24S

HIGH POWER SWITCHING USE
INSULATED TYPE

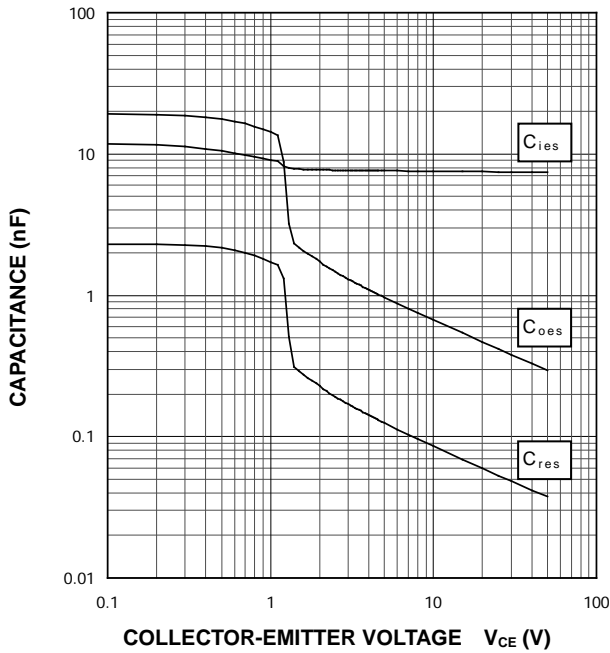
PERFORMANCE CURVES

INVERTER PART

CAPACITANCE CHARACTERISTICS

(TYPICAL)

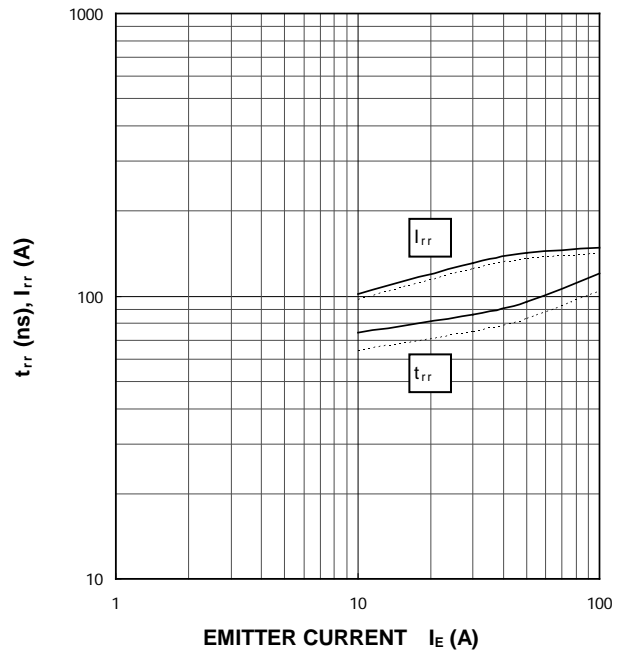
G-E short-circuited, $T_j=25\text{ }^\circ\text{C}$



FREE WHEELING DIODE REVERSE RECOVERY CHARACTERISTICS

(TYPICAL)

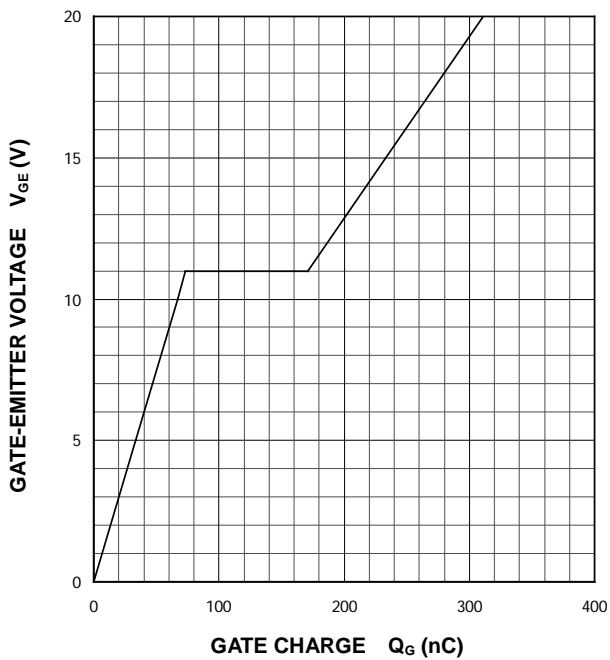
$V_{CC}=600\text{ V}$, $V_{GE}=\pm 15\text{ V}$, $R_G=6.2\ \Omega$, INDUCTIVE LOAD
—: $T_j=150\text{ }^\circ\text{C}$, - - - -: $T_j=125\text{ }^\circ\text{C}$



GATE CHARGE CHARACTERISTICS

(TYPICAL)

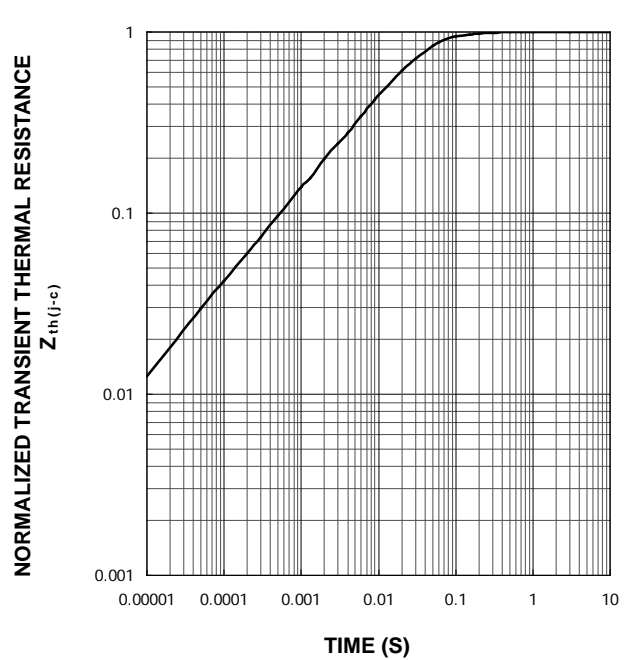
$V_{CC}=600\text{ V}$, $I_C=100\text{ A}$, $T_j=25\text{ }^\circ\text{C}$



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS

(MAXIMUM)

Single pulse, $T_C=25\text{ }^\circ\text{C}$
 $R_{th(j-c)Q}=0.20\text{ K/W}$, $R_{th(j-c)D}=0.29\text{ K/W}$

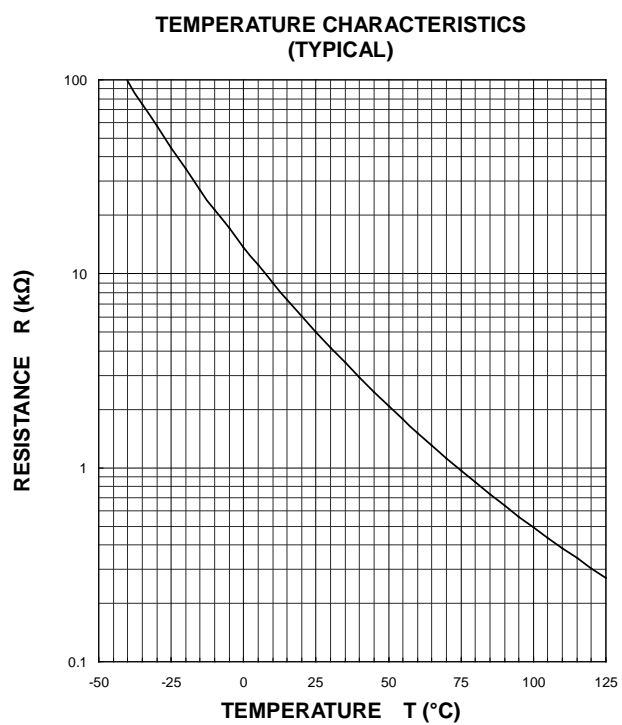


CM100TX-24S

HIGH POWER SWITCHING USE
INSULATED TYPE

PERFORMANCE CURVES

NTC thermistor part



Keep safety first in your circuit designs!

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